

**Section** \_\_\_\_\_

HV Multifunction

**Application** \_\_\_\_\_

Field  
Laboratory  
Production



**PRODUCT BENEFITS**

No silicone  
Ball bearings for an easier rotation of the tool  
Low roughness over insulation

**TOOL CAPACITY**

<b>Diameter</b>	40 - 90 mm 1,575 - 3,543 inch
<b>Bonded semicon thickness capacity</b>	2,5 mm / 0,098 in
<b>Remaining length of the semicon</b>	55 mm / 2,165 in
<b>Insulation thickness capacity</b>	35 mm / 1,378 in
<b>Guiding</b>	By ball bearings

**TOOL DIMENSIONS**

<b>Length</b>	460 mm
<b>Width</b>	155 mm
<b>Height</b>	150 mm
<b>Weight without box</b>	3,9 Kg
<b>Packaging</b>	Case

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## Multifunction tool for bonded semiconductor and insulation

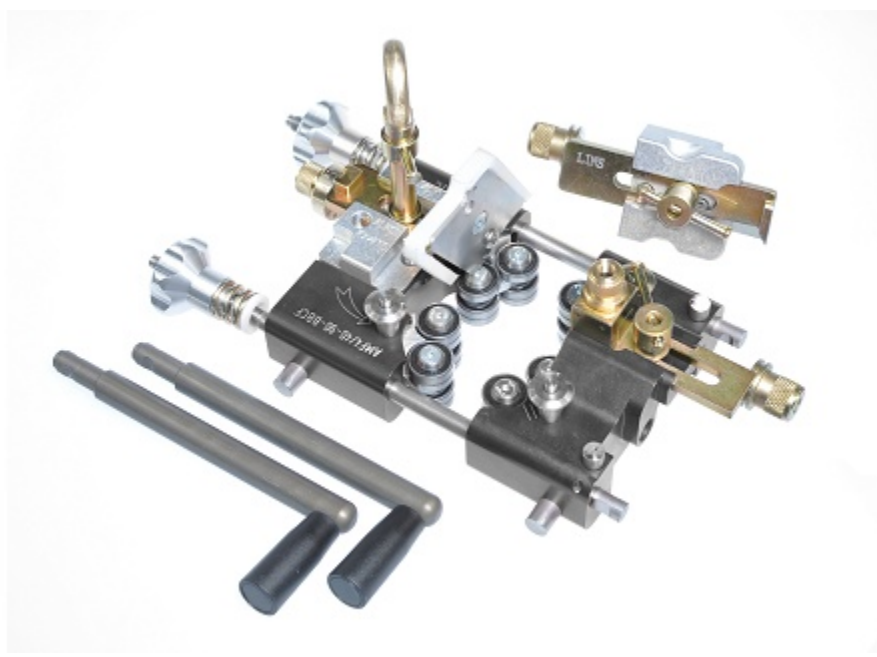
**TO DO WHAT**

The CAMF4/40-90-BBCF enables the user :  
-To remove the bonded semiconductor  
-To remove the insulation

The ball bearings in contact with the cable enable an easy rotation of the tool

Bonded semiconductor removal : Very steady (16 ball bearings rolling around the cable), shaping the cable round over the insulation , constant diameter over the insulation, prevent the blade from digging into the insulation, perform a chamfer on transition between the insulation and the semiconductor

Insulation removal : Back-iron that enables the user to tune the pitch of the tool thus making the rotation of the tool easy when removing the insulation



**Options**

- BMF/40-90 - Thrust to stop the tool
- K7/PNS4 - Blade support to make groove/slot
- K7/SNS4 - To remove semiconductor with straight transition between insulation and semi

**Spare part**

- LFNS - Spare blade for bonded semiconductor
- LINS - Spare blade for insulation

**Associated tool**

- DMSR/40-90 - Reinforced stripping tool for hard outer sheath (PE, PEHD, Lead)
- CHN4/50-110 NS - Tool to taper XLPE insulation
- GRI - Scraper for residues of bonded semiconductor

HV cables Tools

# CAMF4/40-90-BBCF



Part Number	Diameter	Tool capacity				Dimensions			Packaging
		Bonded semicon thickness capacity	Remaining length of the semicon	Insulation thickness capacity	Guiding	Length	Width	Height	
<b>CAMF4/40-90-BBCF</b>	40 - 90 mm 1,575 - 3,543 in	2,5 mm / 0,098 in	55 mm / 2,165 in	35 mm / 1,378 in	By ball bearings	460 mm 18,110 in	155 mm 6,102 in	150 mm 5,906 in	case
<b>CAMF5/55-160-BBCF</b>	55 - 160 mm 2,165 - 6,299 in	3 mm / 0,118 in	80 mm / 3,150 in	35 mm / 1,378 in	By ball bearings	700 mm 27,559 in	255 mm 10,039 in	180 mm 7,087 in	case